09-20-1999

'M COVER SHEET

To the Honorable Commissione	September 3, 1999 Attorney Dkt: 5649-765
Please record the attached o 101148645	
1. Name of conveying party(ies):	2. Name and address of receiving party(ies):
S-Hyeong Lee Jong-Heui Song Min-Woong Choi	Samsung Electronics Co., Ltd. 416 Maetan-dong, Paldal-gu Suwon-City, Kyungki-do Republic of Korea
Additional name(s) of conveying party(ies) attached? Yes X No	
3. Nature of conveyance:	36
X Assignment Merger Security Agreement Change of Name Other Execution Date: August 31, 1999	
Execution Date. August 31, 1999	Additional name(s) & address(es) attached? Yes X No
4. Application Serial No. Pate If this document is being filed together with a new application, is: August 25, 1999; August 29, 1999; August 31, 1999 Additional numbers attached? Yes X No 5. Name and address of party to whom correspondence concerning document should be mailed: Grant J. Scott Myers Bigel Sibley & Sajovec P.O. Box 37428	
FC:581 40.00 GP	8. Deposit account number: 50-0220
(Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE	
9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Robert W. Glatz, Reg. 36,811 Signature Total number of pages including cover sheet, attachments and document: 3	

PATENT REEL: 010233 FRAME: 0862

ASSIGNMENT

THIS ASSIGNMENT, made by us, Se-Hyeong Lee, a citizen of the Republic of Korea, residing at 611-601, Ssangyong Apt., Pureun town, Sunae-dong, Bundang-ku, Sungnam-shi, Kyunggi-do, Republic of Korea; Jong-Heui Song, a citizen of the Republic of Korea, residing at 611-1104, Bosung Apt., 1265, Kwonsun-dong, Kwonsun-ku, Suwon, Kyunggi-do, Republic of Korea; and Min-Woong Choi, a citizen of the Republic of Korea, residing at 102-802, Donga Apt., 645-2, Junnong1-dong, Dongdaemoon-ku, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in PLASMA ETCHING APPARATUS HAVING A SEALING MEMBER COUPLING AN UPPER ELECTRODE TO AN ETCHING CHAMBER for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. ________, filed _______) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as

PATENT REEL: 010233 FRAME: 0863 fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, we have hereunto set our hands and seals on this 31th day of 4 yest , 19 99.

Se-Hyeong Lee

Se-Hyeong Lee

Jong-Heui Song

Jong-Heui Song

Min-weeng chai

Min-Woong Choi

Witnessed by:

Baskin

Date: 1999. A. 25

Kim Je-Youn

Date: 99 4 29

Lim Un-Young

Date: 99 8 3/

RECORDED: 09/03/1999